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SUBMISSION TYPE:	NEW ASSIGNMENT
NATURE OF CONVEYANCE:	ASSIGNMENT

CONVEYING PARTY DATA

Name	Execution Date
Byung Tai Do	09/20/2007
II Kwon Shim	09/20/2007
Antonio B. Dimaano Jr.	09/20/2007
Heap Hoe Kuan	09/20/2007

RECEIVING PARTY DATA

Name:	STATS ChipPAC Ltd.		
Street Address:	5 Yishun Street 23		
City:	Singapore		
State/Country:	SINGAPORE		
Postal Code:	768442		

PROPERTY NUMBERS Total: 1

Property Type	Number
Application Number:	11858554

CORRESPONDENCE DATA

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ATTORNEY DOCKET NUMBER: 27-454

NAME OF SUBMITTER: Mikio Ishimaru

Total Attachments: 3

PATENT REEL: 019855 FRAME: 0762

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> PATENT REEL: 019855 FRAME: 0763

Docket No.: 27-454

ASSIGNMENT

WHEREAS, the undersigned (hereinafter termed Assignor(s)) has/have invented certain new and useful improvements in

INTEGRATED CIRCUIT PACKAGE SYSTEM WITH WARP-FREE CHIP

for which a United States patent application has been executed on or before the date of this assignment;

WHEREAS, <u>STATS ChipPAC Ltd.</u>, a Corporation of the <u>Republic of Singapore</u>, having a place of business at <u>5 Yishun Street 23</u>, <u>Singapore 768442</u> (hereinafter termed Assignee), is desirous of acquiring the entire right, title and interest in and to said application and said invention and improvements thereon, and in and to Letters Patents thereon when granted in the United States and foreign countries;

NOW, THEREFORE, for good and valuable consideration received by said Assignor(s) from said Assignee, the receipt of which is hereby acknowledged by said Assignor(s):

- 1. Said Assignor(s) does hereby sell, assign, transfer and convey unto said Assignee, the entire right, title and interest in and to said application and said invention and in and to any and all improvements on said invention and in and to any and all improvements on said invention heretofore or hereafter made or acquired by said Assignor(s); and in and to any and all Letters Patent on said invention and/or said improvements that may be granted in the United States or any foreign country, including each and every Letters Patent granted on any application which is a division, continuation, substitution, renewal, or continuation-in-part of any said application, and in and to each and every reissue or extension of said Letters Patent.
- Said Assignor(s) hereby covenants and agrees to cooperate with said Assignee where said Assignee may enjoy to the fullest extent the right, title and interest herein conveyed. Such cooperation shall include (a) prompt execution of all papers (prepared at the expense of Assignee) which are deemed necessary or desirable by Assignee to perfect in it the right, title and interest herein conveyed, (b) prompt execution of all petitions, oaths, specifications or other papers (prepared at the expense of Assignee) which are deemed necessary or desirable by assignee for prosecuting said application, for filing and prosecuting divisional, continuation, substitution, renewal, continuation-in-part, or additional applications in the United States and/or foreign countries covering said invention and/or said improvements, for filing and prosecuting applications for reissuance of letters patent included herein, or for interference proceedings involving said invention and/or said improvements and (c) prompt assistance and cooperation in the prosecution of interference proceedings involving said invention and/or said improvements and in the adjudication of said Letters Patent, particularly by the disclosure of facts and the production of evidence relating to said invention and/or said improvements, provided the expenses which may be incurred by said Assignor(s) in lending such assistance and cooperation shall be paid by the Assignee.
- 3. The terms, covenants and conditions of this assignment shall inure to the benefit of said Assignee, its successors, assigns and/or other legal representatives and shall be binding upon said Assignor(s), his/her heirs, legal representatives and assigns.
- 4. Said Assignor(s) hereby warrants and represents that he/she has not entered into any assignment, contract or understanding in conflict herewith.

PATENT REEL: 019855 FRAME: 0764 IN WITNESS WHEREOF, the said Assignor has executed and delivered this instrument on the date set forth below.

- Star	Sep. 20. 2007	
-Byung Tai Do	Date	
	deits	
Witness Signature	Witness Signature	
HUANG RUI	DISCOPO MERILO	
Print Witness Name	Print Witness Name	
20 (ep 2507	20 CEPT. 2007	
Date	Date	

IN WITNESS WHEREOF, the said Assignor has executed and delivered this instrument on the date set forth below.



the date set forth below.

IN WITNESS WHEREOF	the said Assignor h	as executed and	delivered this	instrument on

Date

Antonio B. Dimaano Jr.

Date

Antonio B. Dimaano Jr.

Witness Signature

JOSE ALVIN CAPAMS

Print Witness Name

20 | Sept. | 2007

Docket No.: 27-454 ASSIGNMENT

IN WITNESS WHEREOF, the said Assignor has executed and delivered this instrument on the date set forth below.

Heap Hoe Kuan

Witness Signature Witness Signature

GOH HIN HWA CHOW SENG GUAN Print Witness Name

Print Witness Name

20 Sept 2007 20 Sep 2007 Date Date